# 2N6426, 2N6427

2N6426 is a Preferred Device

# **Darlington Transistors**

# **NPN Silicon**

### **Features**

• These are Pb-Free Devices\*

### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V <sub>CEO</sub>	40	Vdc
Collector - Base Voltage	V <sub>CBO</sub>	40	Vdc
Emitter – Base Voltage	V <sub>EBO</sub>	12	Vdc
Collector Current – Continuous	Ic	500	mAdc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	625 5.0	mW mW/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

### THERMAL CHARACTERISTICS

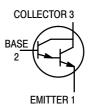
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	°C/W

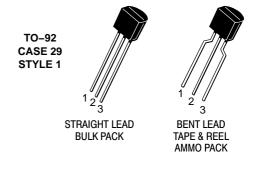
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



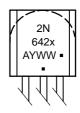
# ON Semiconductor®

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# **MARKING DIAGRAM**



x = 6 or 7

A = Assembly Location

Y = Year

WW = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

## **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

**Preferred** devices are recommended choices for future use and best overall value.

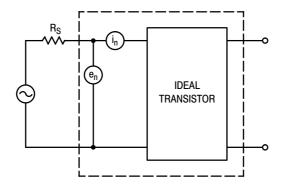
<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# 2N6426, 2N6427

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS			•			
Collector – Emitter Breakdown Voltage, (Note 1) (I <sub>C</sub> = 10 mAdc, V <sub>BE</sub> = 0)		V <sub>(BR)CEO</sub>	40	-	_	Vdc
Collector – Base Breakdown Voltage ( $I_C = 100 \mu Adc, I_E = 0$ )		V <sub>(BR)CBO</sub>	40	-	_	Vdc
Emitter – Base Breakdown Voltage ( $I_E = 10 \mu Adc, I_C = 0$ )		V <sub>(BR)EBO</sub>	12	-	_	Vdc
Collector Cutoff Current (V <sub>CE</sub> = 25 Vdc, I <sub>B</sub> = 0)		I <sub>CES</sub>	-	-	1.0	μAdc
Collector Cutoff Current (V <sub>CB</sub> = 30 Vdc, I <sub>E</sub> = 0)		I <sub>CBO</sub>	-	-	50	nAdc
Emitter Cutoff Current (V <sub>EB</sub> = 10 Vdc, I <sub>C</sub> = 0)		I <sub>EBO</sub>	-	-	50	nAdc
ON CHARACTERISTICS						
DC Current Gain, (Note 1) (I <sub>C</sub> = 10 mAdc, V <sub>CE</sub> = 5.0 Vdc)	2N6426 2N6427	h <sub>FE</sub>	20,000 10,000	- -	200,000 100,000	_
$(I_C = 100 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc})$	2N6426 2N6427		30,000 20,000	- -	300,000 200,000	
$(I_C = 500 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc})$	2N6426 2N6427		20,000 14,000	- -	200,000 140,000	
Collector – Emitter Saturation Voltage ( $I_C$ = 50 mAdc, $I_B$ = 0.5 mAdc) ( $I_C$ = 500 mAdc, $I_B$ = 0.5 mAdc		V <sub>CE(sat)</sub>		0.71 0.9	1.2 1.5	Vdc
Base – Emitter Saturation Voltage (I <sub>C</sub> = 500 mAdc, I <sub>B</sub> = 0.5 mAdc)		V <sub>BE(sat)</sub>	-	1.52	2.0	Vdc
Base – Emitter On Voltage (I <sub>C</sub> = 50 mAdc, V <sub>CE</sub> = 5.0 Vdc)		V <sub>BE(on)</sub>	_	1.24	1.75	Vdc
SMALL-SIGNAL CHARACTERISTICS						
Output Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)		C <sub>obo</sub>	-	5.4	7.0	pF
Input Capacitance ( $V_{EB} = 1.0 \text{ Vdc}$ , $I_{C} = 0$ , $f = 1.0 \text{ MHz}$ )		C <sub>ibo</sub>	_	10	15	pF
Input Impedance ( $I_C = 10 \text{ mAdc}$ , $V_{CE} = 5.0 \text{ Vdc}$ , $f = 1.0 \text{ kHz}$ )	2N6426 2N6427	h <sub>ie</sub>	100 50	- -	2000 1000	kΩ
Small–Signal Current Gain ( $I_C = 10 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc}, f = 1.0 \text{ kHz}$ )	2N6426 2N6427	hfe	20,000 10,000	1 1		_
Current – Gain – High Frequency (I <sub>C</sub> = 10 mAdc, V <sub>CE</sub> = 5.0 Vdc, f = 100 MHz)	2N6426 2N6427	h <sub>fe</sub>	1.5 1.3	2.4 2.4	- -	-
Output Admittance ( $I_C = 10 \text{ mAdc}$ , $V_{CE} = 5.0 \text{ Vdc}$ , $f = 1.0 \text{ kHz}$ )		h <sub>oe</sub>	-	-	1000	μmhos
Noise Figure (I <sub>C</sub> = 1.0 mAdc, $V_{CE}$ = 5.0 Vdc, $R_S$ = 100 k $\Omega$ , f = 1.0 kHz)		NF	-	3.0	10	dB

<sup>1.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s; Duty Cycle  $\leq$  2.0%.



**Figure 1. Transistor Noise Model** 

# **NOISE CHARACTERISTICS**

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}C)$ 

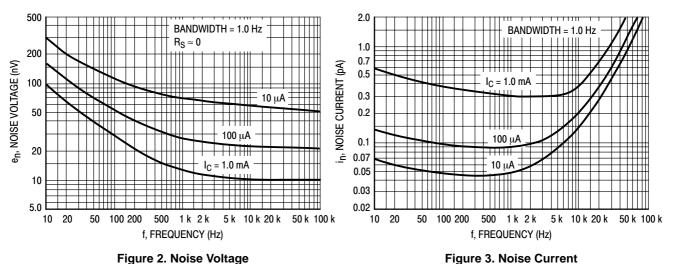


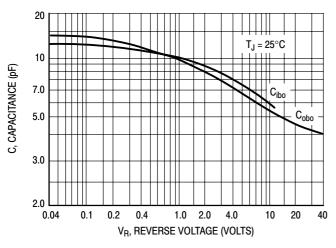
Figure 2. Noise Voltage

200 V<sub>T</sub>, TOTAL WIDEBAND NOISE VOLTAGE (nV) BANDWIDTH = 10 Hz TO 15.7 kHz 12 BANDWIDTH = 10 Hz TO 15.7 kHz 100 NF, NOISE FIGURE (dB) 10 70  $I_C = 10 \mu A$ 10 μA 8.0 50 100 μΑ 6.0 100 μΑ 30 4.0 I<sub>C</sub> = 1.0 mA 20 1.0 mA 2.0 1.0 2.0 100 200 500 2.0 20 50 1000 1.0 5.0 20 50 100 500 1000  $R_S$ , SOURCE RESISTANCE ( $k\Omega$ )  $R_S$ , SOURCE RESISTANCE ( $k\Omega$ )

Figure 4. Total Wideband Noise Voltage

Figure 5. Wideband Noise Figure

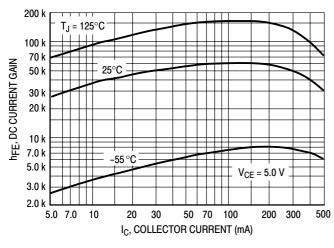
# **SMALL-SIGNALCHARACTERISTICS**



 $V_{CE}$  = 5.0 V |hfe|, SMALL-SIGNAL CURRENT GAIN f = 100 MHz  $T_J = 25^{\circ}C$ 2.0 1.0 0.8 0.6 0.4 0. 1.0 2.0 0.5 20 50 100 200 500 0.5 10 IC, COLLECTOR CURRENT (mA)

Figure 6. Capacitance

Figure 7. High Frequency Current Gain



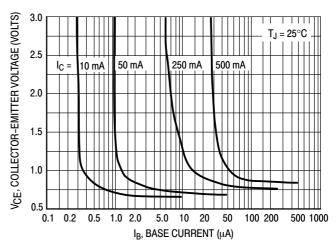
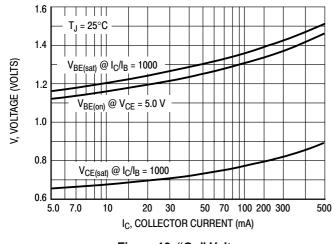


Figure 8. DC Current Gain

Figure 9. Collector Saturation Region



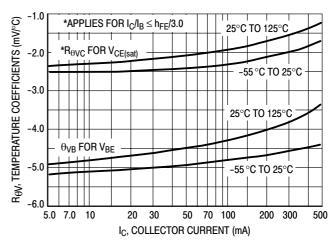


Figure 10. "On" Voltages

Figure 11. Temperature Coefficients

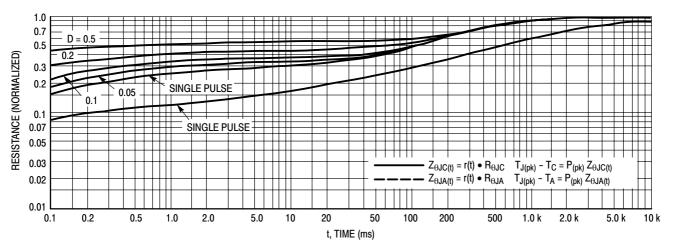


Figure 12. Thermal Response

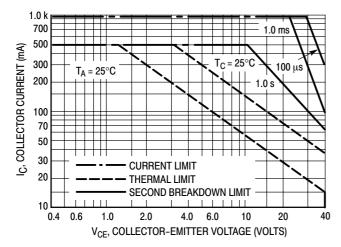
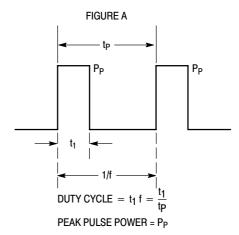


Figure 13. Active Region Safe Operating Area



Design Note: Use of Transient Thermal Resistance Data

# **ORDERING INFORMATION**

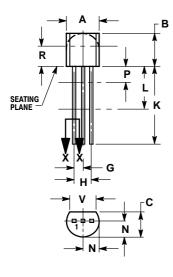
Device	Package	Shipping <sup>†</sup>
2N6426G	TO-92 (Pb-Free)	5,000 Units / Bulk
2N6426RLRAG	TO-92 (Pb-Free)	2,000 / Tape & Ammo
2N6427G	TO-92 (Pb-Free)	5,000 Units / Bulk
2N6427RLRAG	TO-92 (Pb-Free)	2,000 / Tape & Ammo

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# 2N6426, 2N6427

## PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 **ISSUE AM** 



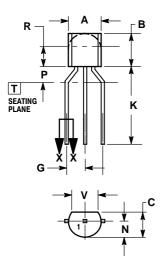
STRAIGHT LEAD **BULK PACK** 



### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
P		0.100		2.54
R	0.115		2.93	
v	0.135		3 43	



**BENT LEAD** TAPE & REEL AMMO PACK



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
  CONTOUR OF PACKAGE BEYOND
- DIMENSION R IS UNCONTROLLED
- LEAD DIMENSION IS UNCONTROLLED IN PAND BEYOND DIMENSION K MINIMUM.

	MILLIMETERS		
DIM	MIN MAX		
Α	4.45	5.20	
В	4.32	5.33	
С	3.18	4.19	
D	0.40	0.54	
G	2.40	2.80	
J	0.39	0.50	
K	12.70		
N	2.04	2.66	
Р	1.50	4.00	
R	2.93		
٧	3.43		

STYLE 1:

PIN 1 FMITTER

BASE

COLLECTOR

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